

* 1255 SERIES ZIF SYSTEM CONNECTOR *

This product specification contains the test method. The following datum are the general performance and requirements of the Leoco 1255 series ZIF connector.

1. Construction and dimensions shall be in accordance with the referenced drawing.

产品结构 and 尺寸依据所提的产品图面

2. Characteristics 特性:

Current rating 额定电流: 1A AC,DC

Voltage rating 额定电压: 200V AC,DC

Temperature rating 额定温度: -20°C ~+85°C

Applicable wire 适用线材: FCC and FPC

3. Electrical performance 电气特性: :

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法及条件	REQUIREMENT 要求
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method 3004.1 of MIL-STD-1344A.	20 mΩ max
3-2	Insulation Resistance 绝缘电阻	It should be tested in accordance with method 3003.1 of MIL-STD-1344A.	500 MΩ min
3-3	Dielectric Withstanding Voltage 耐电压	The connector shall be tested in accordance with method 3001.1 of MIL-STD-1344A. When the AC 500 V rms for one minute applied between adjacent contacts.	No evidence of breakdown and flashover.

4. Mechanical Performance 机械特性: :

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法及条件	REQUIREMENT 要求
4-1	Terminal Retention 端子保持力	Apply axial pull out force at the speed of 25 mm/minute one the terminal assembled is the housing.	0.6 kg min.
4-2	FCC/FPC Retention Force FPC 保持力	Retention connector at the speed rate of 25+/-3/minute.(Under 10 circuits)	0.15+0.05 x n circuit(n=3~10) Unit : kgf (min).
		(over 10 circuits)	0.4+0.05 x n circuit(n=11~30) Unit : kgf (min).

5. ENVIRONMENTAL PERFORMANCE 环境特性:

5-1	Salt spray 盐雾测试	Connector shall be tested in accordance with method 1001.1 of MIL-STD-1344A condition B. Temperature: 35+/-2°C. Density: 5% in weight. Period: 48 hours.	No damage . Contact resistance: Less than twice of initial
5-2	Solderability 着锡性	Connector termination ends shall be checked for solderability in accordance with method 208 of MIL-STD-202F. Solder temperature: 245+/-5 °C Immersion period: 5+/-0.5 sec.	No damage. Minium: 95 % of immersed area.
5-3	Resistance to Soldering Heat 耐高温焊接	Specimen shall be mounted on PCB. Solder temperature :260+/-5°C. Immersion period: 5+/-0.5 sec.	No damage and deformation.

APPR BY:

CHKD BY:

SPEC BY: